



GaN half-bridge integrated circuits for power converters

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Revolution in power converters: MOSFET → GaN

■ Silicon power MOSFET

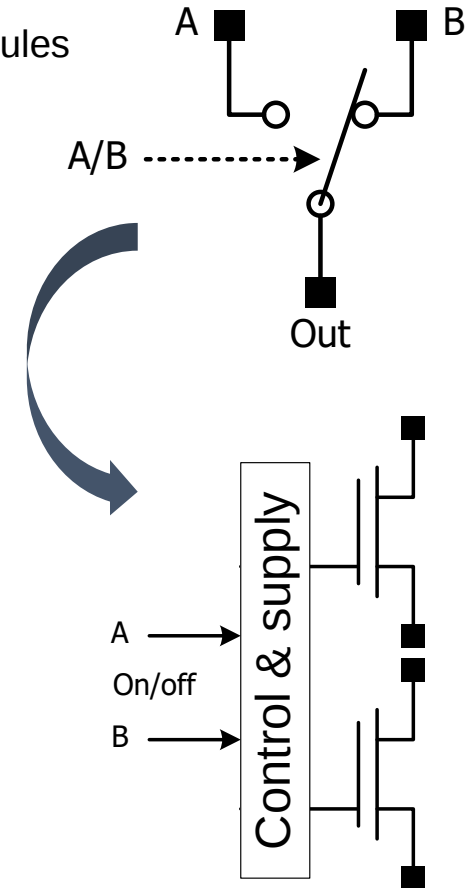
- Specific transistor design for radiation hardening → **rare** → **expensive** & restrictive export control rules apply.
- Bulky → **easier to cool down**.

■ GaN

- Faster switching → **more compact design**
- Lower losses → **better efficiency**
- No (so far) specific transistor design required for radiation hardening
 - Terrestrial automotive grade components produced in volume → lower cost
 - Up-screening & specific SOA for space applications
- Very compact → **a lot more difficult to cool down**

■ Holy Grail for power converter designers = half-bridge module with GaN !

- Supply chain through EU suppliers & foundries → EU independency



Challenges of Driving GaN

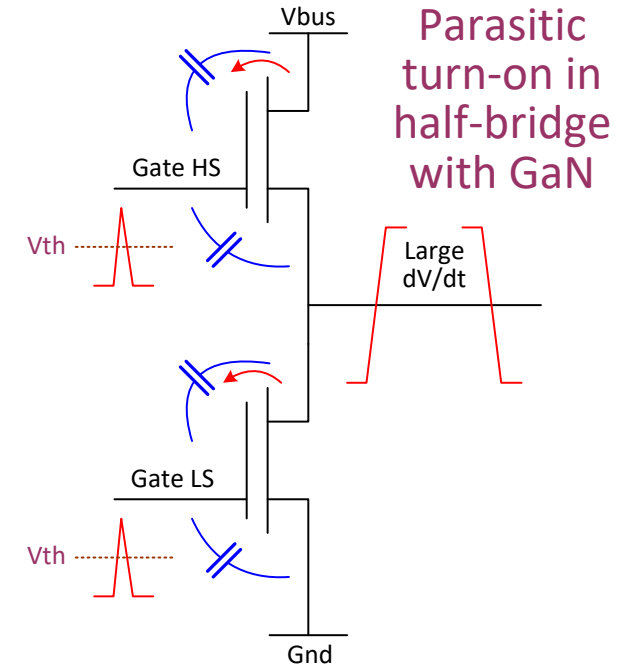
• Pitfalls

■ A GaN HEMT is not a MOSFET:

- Lower and tighter controlled gate turn-on voltage
- Lower threshold voltage (V_{th})
- Significantly faster Turn On and Off times -> High dV/dt
- Lower $C_{gate-source} / C_{drain-gate}$ ratio

⇒ An ideal recipe for expensive fireworks

⇒ Needs an optimized gate-drive approach



Courtesy of MinDCet

Challenges of Driving GaN

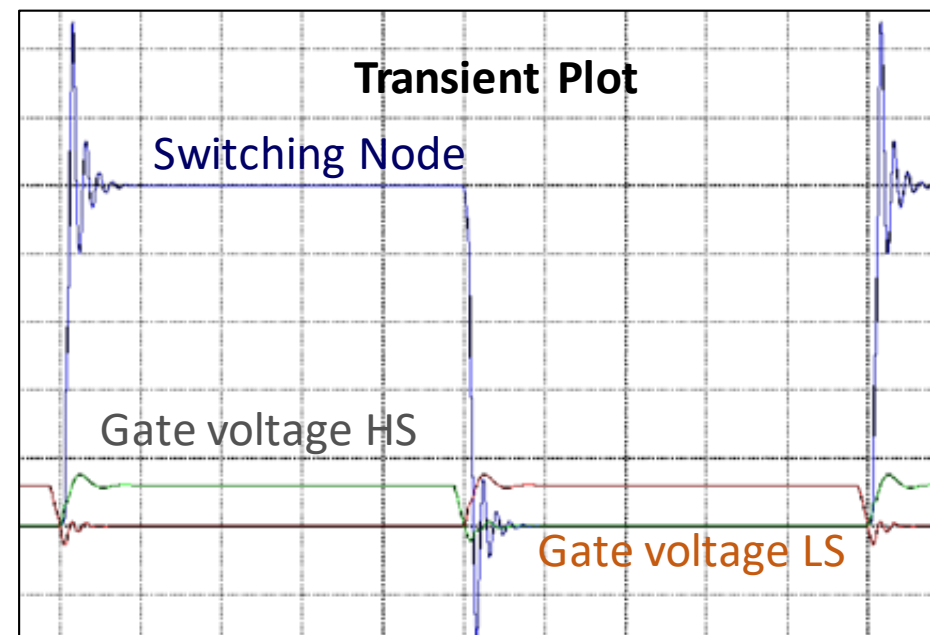
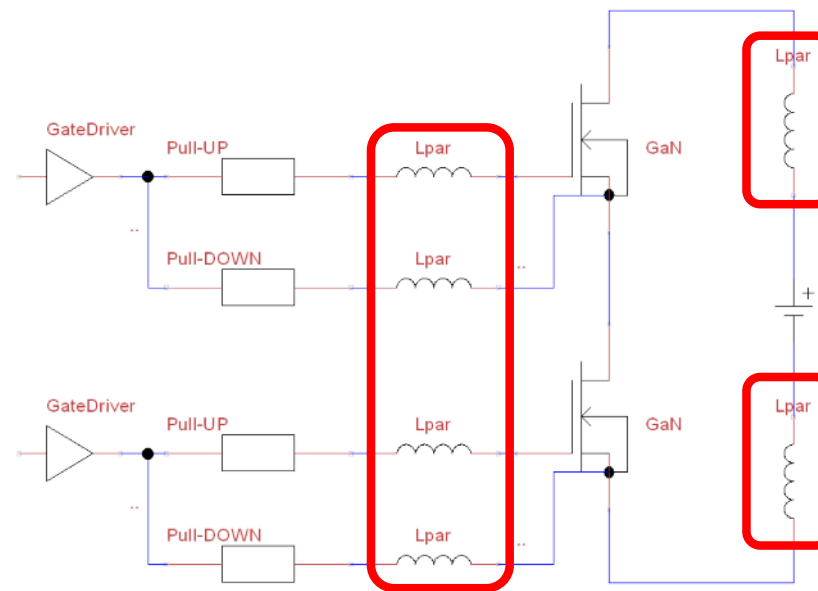
- With an external gate driver:

On PCB level:

- Gate-loop inductance
- Supply inductance
- Gate resistors
- Drain-source inductance

On Gate-driver IC level:

- Dead-time control
- LS/HS delay-matching
- dV/dt immunity
- Negative source voltage from GND inductance
- GaN gate stress with overvoltage

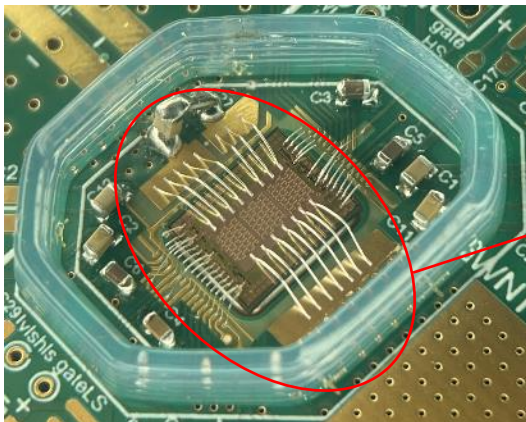
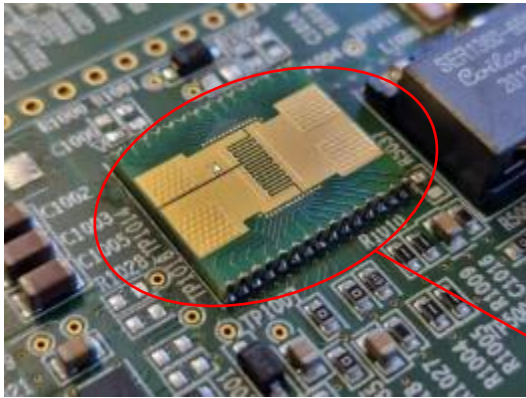


Monolithic GaN Half-bridge + gate driver

Challenges & differences:

Reduce external components in the system

- Increasing the overall system power density
- Strongly drive (high & also low !) GaN up to speed by killing gate-loop parasitics
- Reliability: minimize the gate voltage overshoot
- Require strong isolation between high side & low side power GaN

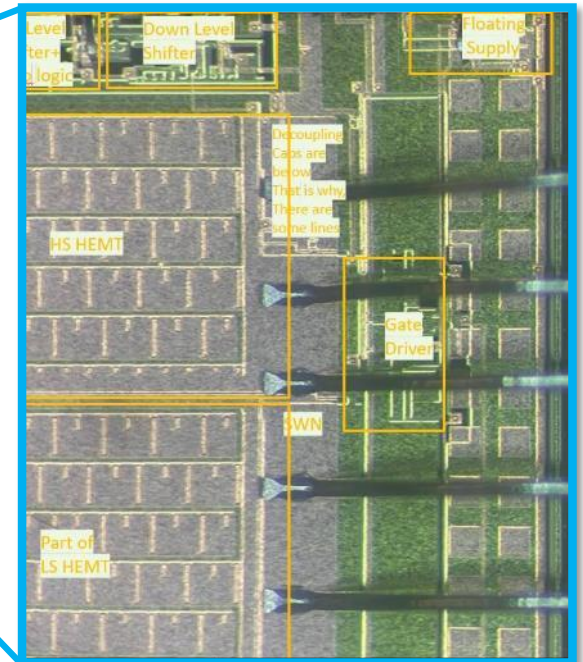
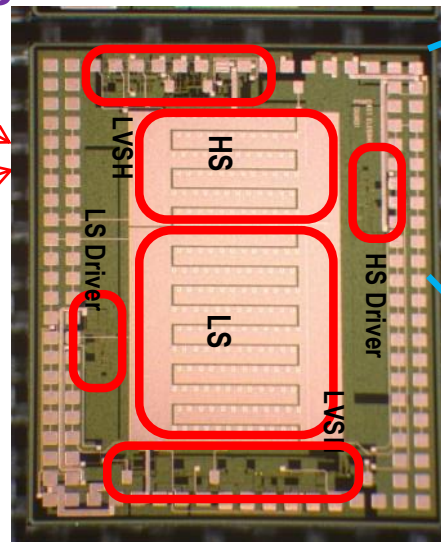


Courtesy of TAS-BE and TAS-FR

Design of full GaN ASIC !

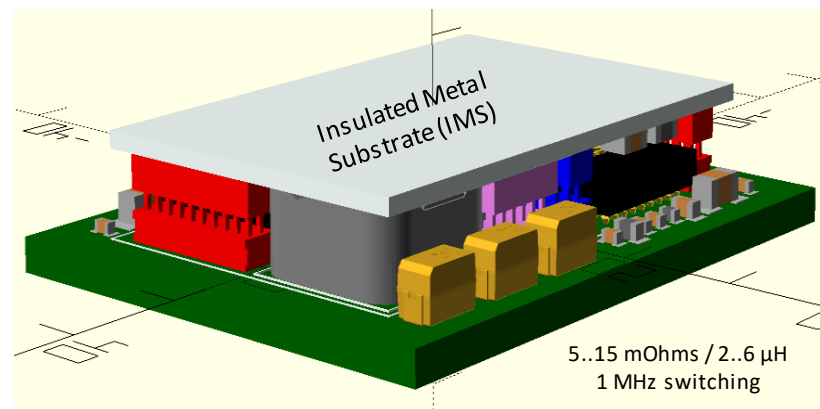
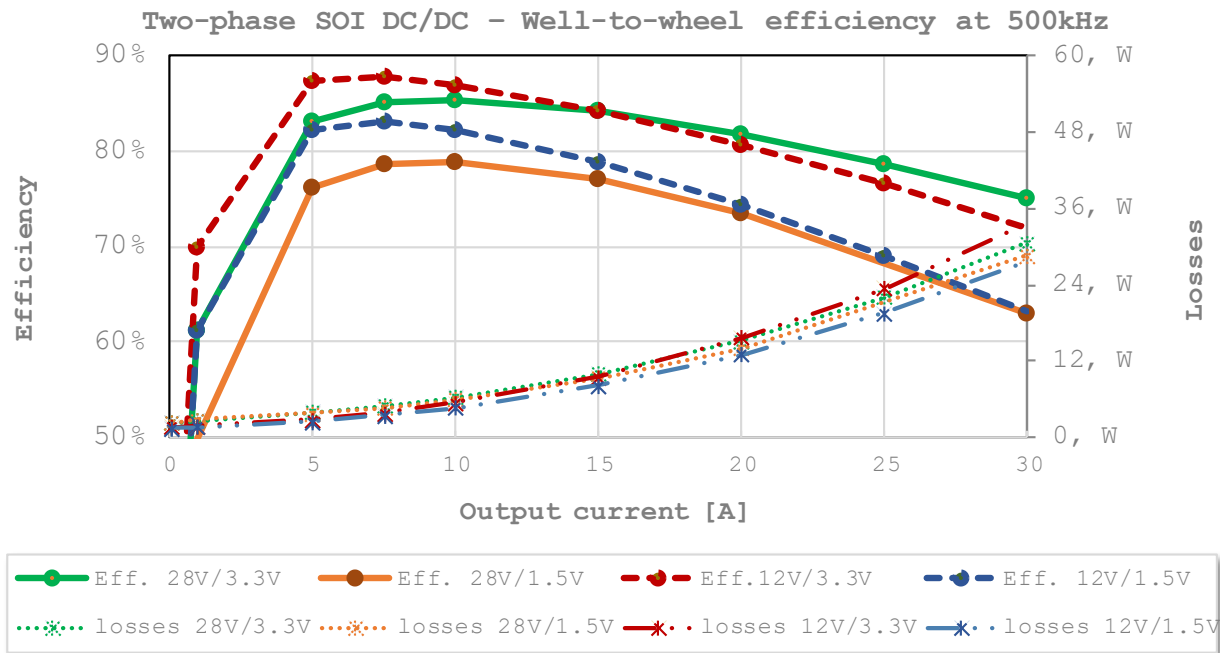
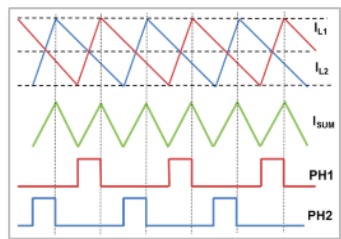
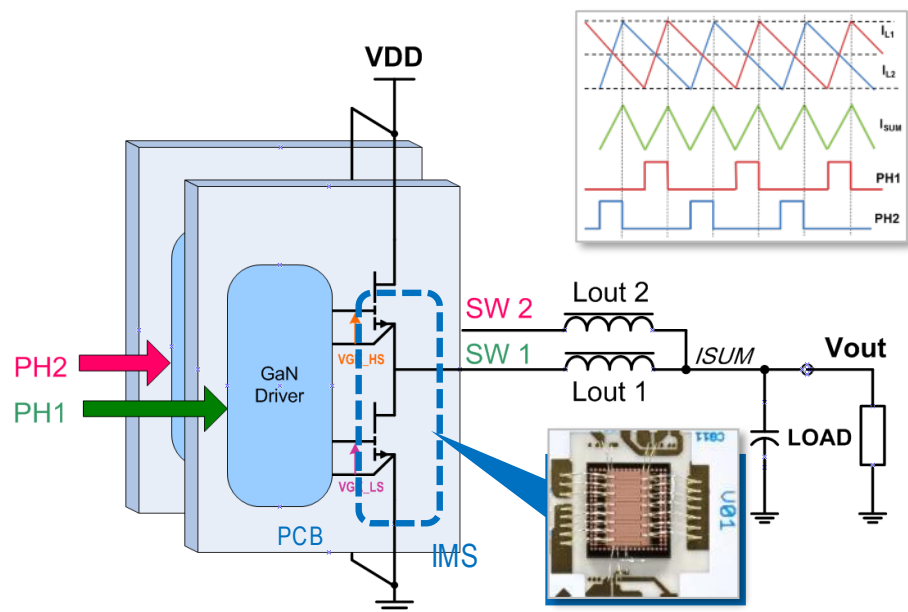
Flip-chip assembly

Wire-bonding assembly

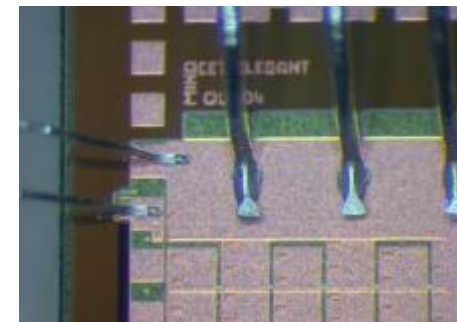
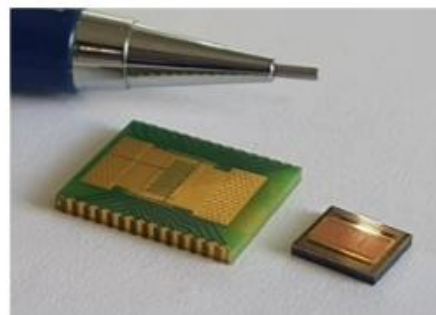
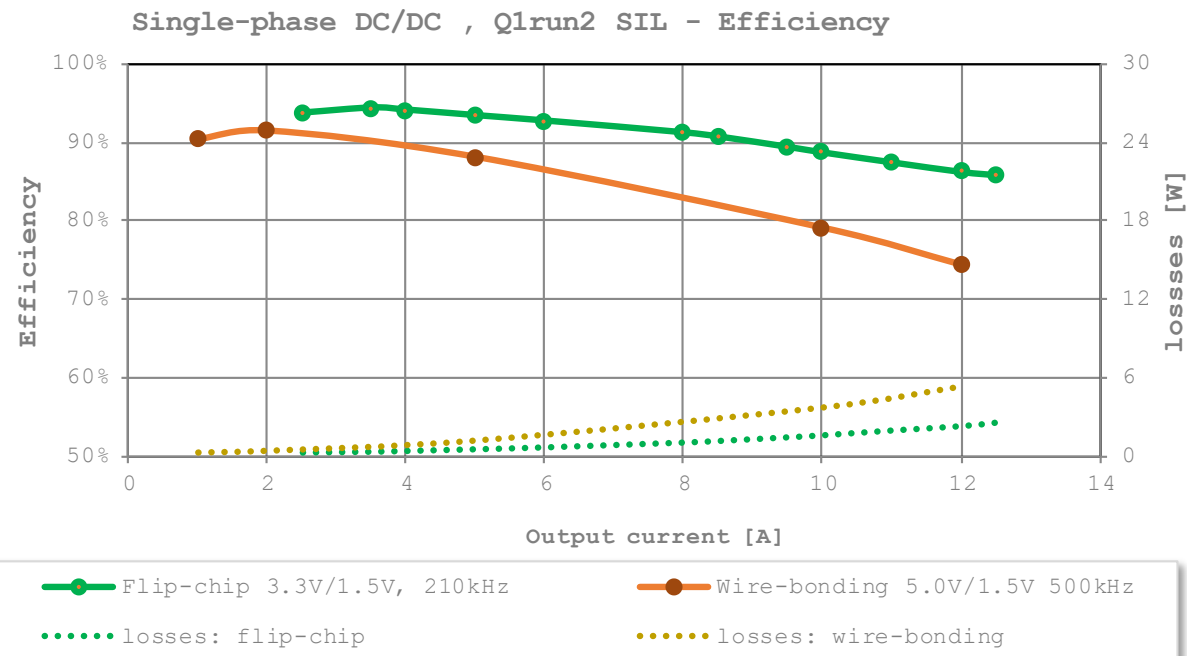
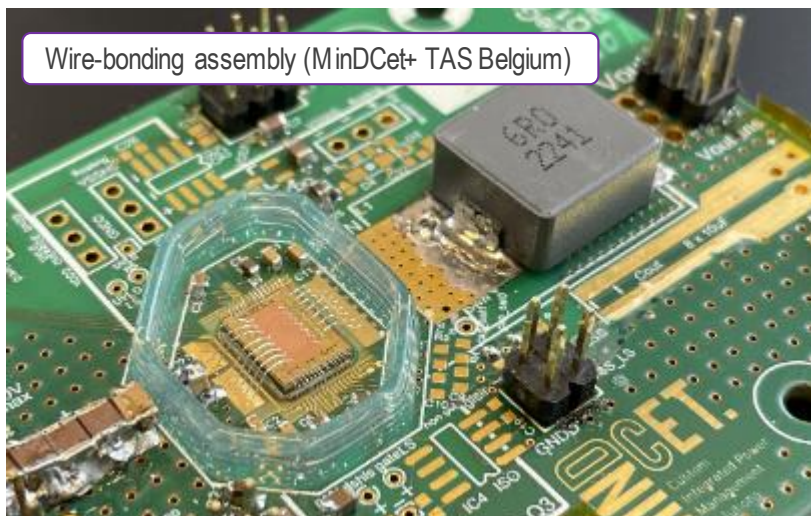
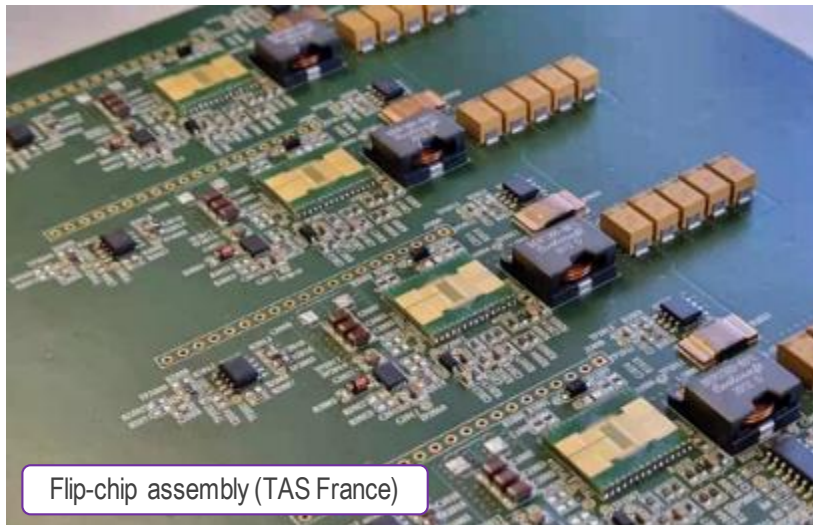


EleGaNT electrical performance: 1st cycle

- Two-phase interleaved synchronous buck
- Power stage composed by 2x EleGaNT (SIL or SOI)
- Vin typ. 12-28V, max. 40V, 30A output, 1MHz ripple output.
- 3.34kW/L output density



EleGaNT electrical performance: 2nd cycle



Courtesy of MinDCet, TAS-BE and TAS-FR

Single Event Effects (SEEs)

- ESCC 25100, $LET_{th} \geq 60 \text{ MeV.cm}^2.\text{mg}^{-1}$

- 1st learning cycle:

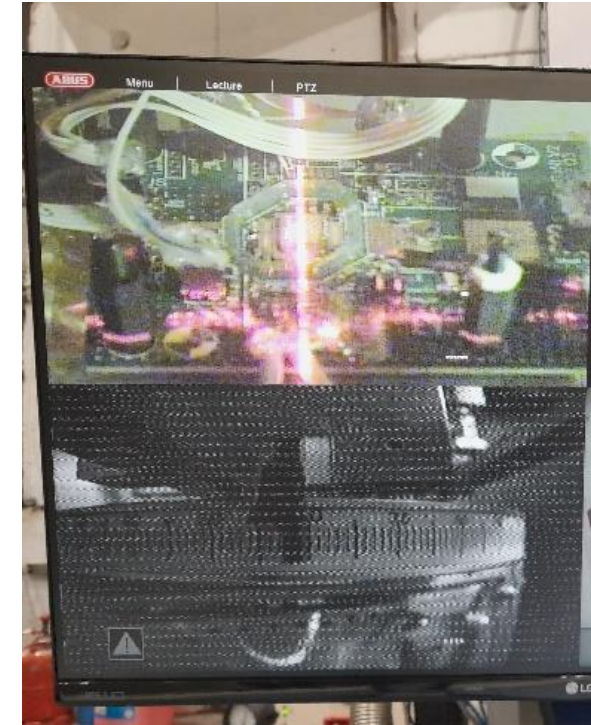
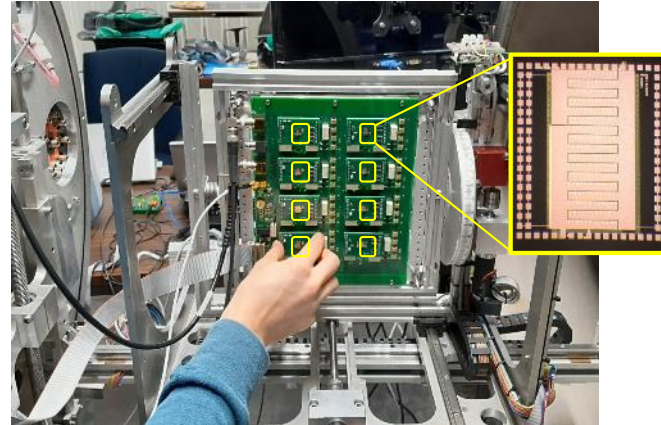
- HEMT half-bridge transistors.

→ No breakdowns or gate rupture to 40V

- 2nd learning cycle: full-chip evaluation

- HEMT half-bridge transistors.
 - Gate drivers for power HEMT
 - Floating supplies for gate driver and level-shifters
 - Level shifters
 - PWM and dead-time generator management

→ No SEEs, no DC/DC failures according to test definition.



RADECS 2022

IEEE TRANSACTIONS ON NUCLEAR SCIENCE
*"Radiation and its Effects on monolithic GaN
 integrated half-bridge for DC-DC converters"*

Total Ionizing Dose (TID)

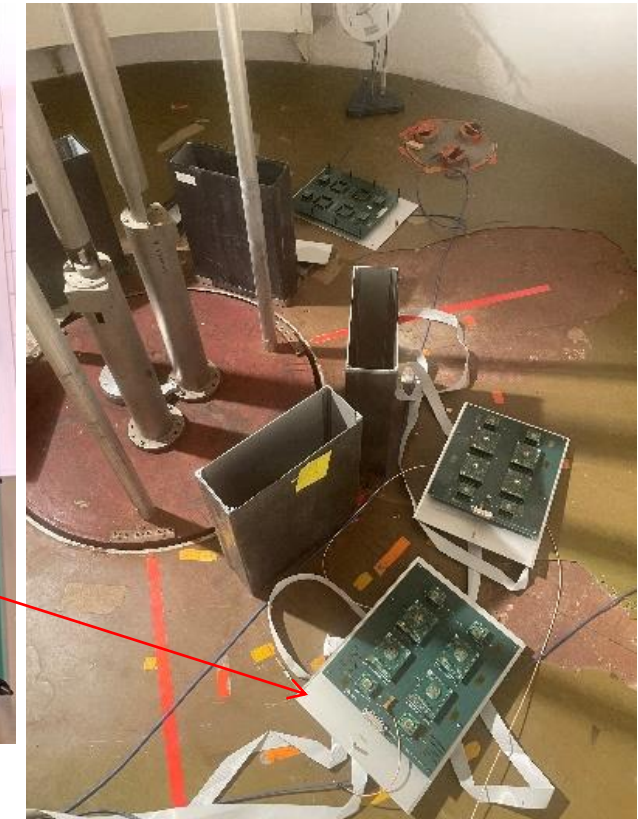
- Inherited 'wide-bandgap' semiconductor properties

- ESCC 22900, 120 krad(Si) equivalent

- HEMT half-bridge transistors.
- Integrated functional blocks
 - Gate drivers for power HEMT
 - Floating supplies for gate driver and level-shifters
 - Level shifters
 - PWM and dead-time generator management

→ No dose drift impact observed

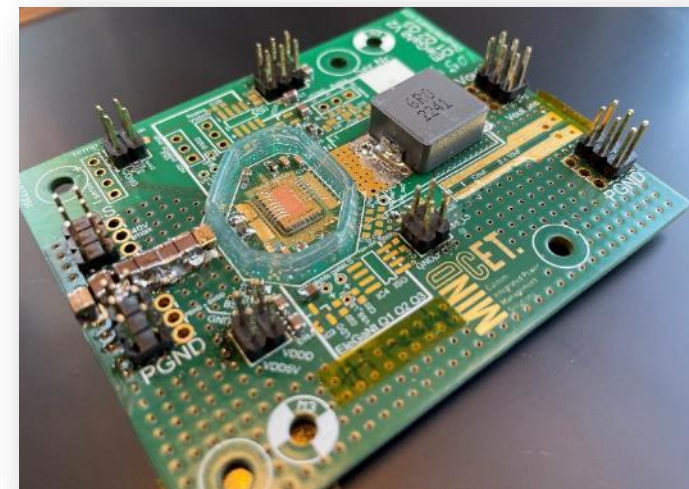
- Gate voltage threshold
- Leakage current at gate and drain
- Propagation delay on level shifters



A new flavor of power ASIC: EleGaNT

■ Impacts for space DC/DC designs:

- Faster switching → more compact
- Lower losses → better efficiency
- Monolithic IC → cheaper & very compact → easy to use
- Fully-configurable with low-volume space-products.



■ Radhard & European technology

- EU export control.

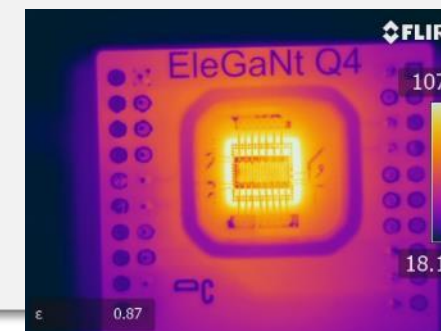
Conventional DC/DC designs

Discrete HS & LS GaN HEMT
Discrete silicon gate driver IC
Discrete gate voltage regulators
Discrete logic signal isolators & level shifters
Discrete opamps and comparators



Monolithic integrated GaN IC: 'many'-in-one solution

Half-bridge: HS & LS GaN
2x gate driver
2x gate voltage regulators
2x PWM logic signal level shifters
PWM & deadtime generator
Temperature sensor
Current sensing





Evolution of integrated GaN program

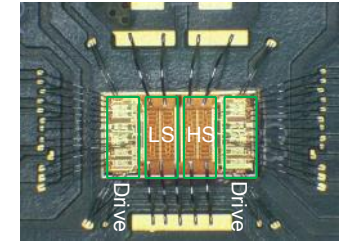


AGENTSCHAP
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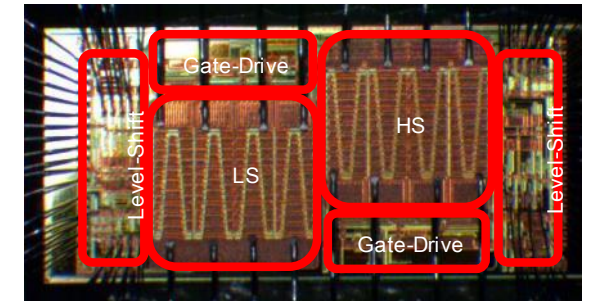
■ First experiments on IMEC technology (2019) in TAS-B

- 200V GaN on SOI
- Flemish region research support → **SloGaN**



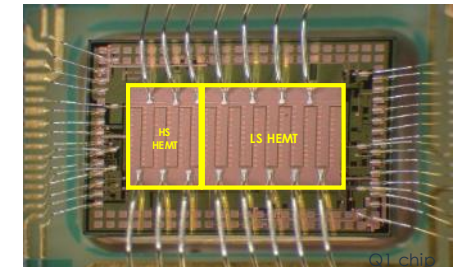
■ Half-bridge IC in GaN for space applications (2022)

- 200V GaN on SOI prototypes in TAS-B
- ESA contract de-risking → **GaN-IC4S**



■ High current – Low-voltage IC for point of load (2024)

- 100V GaN on Silicon/SOI technology → 22-35V space bus
- EU H2020 technology independence → **EleGaNT**



■ NEW step forward !

- Towards Industrialization of GaN integrated circuits → **GaNIC+**



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EleGaNT - Grant Agreement n°101004274



In Extenso
Innovation Croissance

Open

Acknowledgements

Work done by the EleGaNT consortium:



- Technology and PDK provider
- Project Coordinator



- Reliability validation
- Space industry applications



- Passive device development



- IC design and layout



- IP and WP management

Specially thanks to European Commission for granting

